

Amendments to the Claims:

Claims 1, 2, 4, 5, 6, 7, 16, 19, 20, 21, 23, 24, 25, 34, and 35 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) A multi-chip module system comprising:
a substrate having ~~at least~~ a first position having, in turn, a predetermined configuration for locating a first semiconductor device thereat and having a ~~at least one other~~ second position having, in turn, a predetermined configuration for locating a second semiconductor device thereat on the multi-chip module system, the ~~at least one other~~ second position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at the second ~~another~~ position;
a first semiconductor device located in the ~~at least~~ first position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic, said first semiconductor device having been burned in at said ~~at least~~ first position on said substrate; and
a second known-good-die located at the ~~at least one other~~ second position, the second semiconductor device having a second predetermined performance characteristic .
2. (Currently Amended) The multi-chip module system of claim 1, further comprising:
the ~~a at least one other~~ third position having the predetermined configuration for locating the second semiconductor device thereat which is substantially the same as the predetermined configuration of the first position.

3. (Canceled)

4. (Currently Amended) The multi-chip module system of claim 1, further comprising:
the second ~~at least one other~~ position having the predetermined configuration for locating the second semiconductor device thereat; and
the second semiconductor device having a second predetermined performance characteristic of at least substantially twice that of the first predetermined performance characteristic of the first semiconductor device.

5 (Currently Amended) A multi-chip module system comprising:
a substrate having a first position having, in turn, a predetermined configuration for locating a first semiconductor device thereat, having a second position having, in turn, a predetermined configuration for locating a second semiconductor device thereat, and having a ~~at least one other~~ third position having, in turn, a predetermined configuration for locating a third semiconductor device thereat on the multi-chip module system, the ~~at least one other~~ third ~~vacant~~ position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position;
the first semiconductor device located in the first position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic; and
a second known-good-die semiconductor device located in the second position of the substrate for use in the multi-chip module system, the second semiconductor device having a second predetermined performance characteristic, said first and second semiconductor devices have been burned in at said first and second positions, respectively, on said substrate.

6. (Currently Amended) The multi-chip module system of claim 5, further comprising:
the ~~at least one other~~ third position having a predetermined configuration for locating a third semiconductor device thereat which is substantially the same as the predetermined configuration of the first position.

7. (Currently Amended) The multi-chip module system of claim 5, further comprising:
the ~~at least one other~~ third position having a predetermined configuration for locating a third semiconductor device thereat; and
the third semiconductor device having a predetermined performance characteristic substantially similar to that of the first predetermined performance characteristic of the first semiconductor device.

8. (Canceled)

9. (Canceled)

10. (Canceled)

11. (Previously Presented) The multi-chip module system of claim 5, wherein the first semiconductor device comprises a memory device.

12. (Previously Presented) The multi-chip module system of claim 5, wherein the second semiconductor device comprises a memory device.

13. (Previously Presented) The multi-chip module system of claim 5, wherein the first semiconductor device comprises a microprocessor device.

14. (Previously Presented) The multi-chip module system of claim 5, wherein the second semiconductor device comprises a microprocessor device.

15. (Previously Presented) The multi-chip module system of claim 5, wherein the multi-chip module system comprises a single in-line memory module system.

16. (Currently Amended) The multi-chip module system of claim 5, further comprising:
a third semiconductor device; and
an adapter connected to the third semiconductor device, the adapter having a configuration for connecting the adapter to the ~~at least one other~~ third position on the substrate to allow connection of the third semiconductor device to the substrate.

17. (Previously Presented) A multi-chip module system comprising:
a substrate having two opposing sides, said substrate having a first position having, in turn, a predetermined configuration for locating a first semiconductor device thereat, having a second position having, in turn, a predetermined configuration for locating a second semiconductor device thereat, having a third position having, in turn, a predetermined configuration for locating a third semiconductor device thereat, the third position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position, and having a fourth position having, in turn, a predetermined configuration for locating a fourth semiconductor device thereat on the multi-chip module system, the fourth position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position;
the first semiconductor device located in the first position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic; and

a second known-good-die semiconductor device located in the second position of the substrate for use in the multi-chip module system, the second semiconductor device having a second predetermined performance characteristic, said first device being burned in at said first position on said substrate.

18. (Previously Presented) The multi-chip system module of claim 17, wherein: the third position and the fourth position are on opposing sides of the substrate.

19. (Currently Amended) A multi-chip module system comprising:
a substrate having ~~at least~~ a first predetermined configuration position for locating a first semiconductor device thereat and having ~~a at least one other~~ second predetermined configuration position for locating a second semiconductor device thereat on the multi-chip module system, the ~~at least one other~~ second position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position;
the first semiconductor device located in the ~~at least the~~ first predetermined configuration position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic, said first semiconductor device being burned in at said first predetermined configuration position on said substrate; and
a second known-good-die located at the ~~at least one other~~ second predetermined configuration position.

20. (Currently Amended) The multi-chip module system of claim 19, further comprising:
the ~~a at least one other~~ third predetermined configuration position for locating the second semiconductor device thereat which is substantially the same as the predetermined configuration of the first position.

21. (Currently Amended) The multi-chip module system of claim 19, further comprising:
the ~~at least one other~~ third predetermined configuration position having a predetermined configuration for locating the second semiconductor device thereat; and
the second semiconductor device having a predetermined performance characteristic substantially similar to that of the first predetermined performance characteristic of the first semiconductor device.

22. (Canceled)

23. (Currently Amended) A multi-chip module system comprising:
a substrate having a first predetermined configuration position for locating a first semiconductor device thereat, having a second predetermined configuration position for locating a second semiconductor device thereat, and having a ~~at least one other~~ third predetermined configuration position for locating a third semiconductor device thereat on the multi-chip module system, the ~~at least one other~~ third position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position;
the first semiconductor device located in the first predetermined configuration position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic; and
a known-good-die second semiconductor device located in the second predetermined configuration position of the substrate for use in the multi-chip module system, the second semiconductor device having a second predetermined performance characteristic.

24. (Currently Amended) The multi-chip module system of claim 23, further comprising:
the ~~at least one other~~ third predetermined configuration position for locating the third semiconductor device thereat which is substantially the same as the predetermined configuration of the first position.

25. (Currently Amended) The multi-chip module system of claim 23, further comprising:
the ~~at least one other~~ third predetermined configuration position for locating the third semiconductor device thereat; and
the third semiconductor device having a third predetermined performance characteristic substantially similar to that of the first predetermined performance characteristic of the first semiconductor device.

26. (Canceled)

27. (Canceled)

28. (Canceled)

29. (Original) The multi-chip module system of claim 23, wherein the first semiconductor device comprises a memory device.

30. (Original) The multi-chip module system of claim 23, wherein the second semiconductor device comprises a memory device.

31. (Original) The multi-chip module system of claim 23, wherein the first semiconductor device comprises a microprocessor device.

32. (Original) The multi-chip module system of claim 23, wherein the second semiconductor device comprises a microprocessor device.

33. (Original) The multi-chip module system of claim 23, wherein the multi-chip module system comprises a single in-line memory module system.

34. (Currently Amended) The multi-chip module system of claim 23, further comprising:
an adapter connected to the third semiconductor device, the adapter having a configuration for connecting the adapter to the ~~at least one other~~ third predetermined configuration position on the substrate to allow connection of the third semiconductor device to the substrate.

35. (Currently Amended) A multi-chip module system comprising:
a substrate having two opposing sides, said substrate having a first predetermined configuration position for locating a first semiconductor device thereat, having a second predetermined configuration position for locating a second semiconductor device thereat, having a third predetermined configuration position for locating a third semiconductor device thereat, the third predetermined configuration position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position, and having a fourth predetermined configuration for locating a fourth semiconductor device thereat on the multi-chip module system, the fourth ~~second vacant~~ predetermined configuration position having no semiconductor device located thereat until a semiconductor device is installed to replace a defective semiconductor device at another position;
the first semiconductor device located in the first predetermined configuration position of the substrate for use in the multi-chip module system, the first semiconductor device having a first predetermined performance characteristic; and

a known-good-die second semiconductor device located in the second predetermined configuration position of the substrate for use in the multi-chip module system, the second semiconductor device having a second predetermined performance characteristic.

36. (Previously Presented) The multi-chip system module of claim 35, wherein: the third predetermined configuration position and the fourth predetermined configuration position are located on opposing sides of the substrate.